

MiniSKiiP® 3

Converter-Inverter-Brake (CIB)

SKiiP 35NAB12T4V1

Features*

- Trench 4 IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

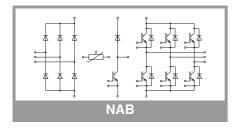
Typical Applications

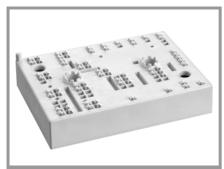
- Inverter up to 26 kVA
- Typical motor power 15 kW

- Max. case temperature limited to T_C=125°C
- Product reliability results valid for T_j≤150°C (recommended T_{i,on}=-40...+150°C)
- T_{j,op}=-40...+150°C)

 MiniSKiiP "Technical Explanations" and "Mounting Instructions" are part of the data sheet. Please refer to both documents for further information

Absolute	Maximum Rating	s		
Symbol	Conditions		Values	Unit
Inverter -	IGBT			
V _{CES}	T _j = 25 °C		1200	V
Ic	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	69	А
T _j = 175 °C		T _s = 70 °C	55	Α
I _C	λ _{paste} =2.5 W/(mK)	T _s = 25 °C	77	А
	T _j = 175 °C	T _s = 70 °C	63	А
I _{Cnom}		•	50	Α
I _{CRM}			150	Α
V _{GES}			-20 20	V
t _{psc}	$V_{CC} = 800 \text{ V}$ $V_{GE} \le 15 \text{ V}$ $V_{CES} \le 1200 \text{ V}$	T _j = 150 °C	10	μs
T _i	020		-40 175	°C
Chopper	- IGBT			ı
V _{CES}	T _i = 25 °C		1200	V
Ic	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	68	Α
	T _i = 175 °C	T _s = 70 °C	55	А
I _C	λ_{paste} =2.5 W/(mK)	T _s = 25 °C	77	А
	T _j = 175 °C	T _s = 70 °C	63	Α
I _{Cnom}	, , , , , , , , , , , , , , , , , , , ,		50	А
I _{CRM}			150	Α
V _{GES}			-20 20	V
t _{psc}	$V_{CC} = 800 \text{ V}$ $V_{GE} \le 15 \text{ V}$ $V_{CES} \le 1200 \text{ V}$	T _j = 150 °C	10	μs
T _i	OLO	1	-40 175	°C
Inverse -	Diode			l
V _{RRM}	T _i = 25 °C		1200	V
I _F	$\lambda_{\text{paste}} = 0.8 \text{ W/(mK)}$	T _s = 25 °C	60	A
	$T_i = 175 ^{\circ}\text{C}$	T _s = 70 °C	48	Α
l _F	λ_{paste} =2.5 W/(mK)	T _s = 25 °C	68	Α
· ·	$T_i = 175 ^{\circ}\text{C}$	T _s = 70 °C	54	Α
I _{FRM}		1 0	150	А
I _{FSM}	$t_p = 10 \text{ ms}, \sin 180^\circ$	°, T _i = 150 °C	270	А
T _i	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	· , -	-40 175	°C
	eling - Diode			
V _{RRM}	T _i = 25 °C		1200	V
I _F	$\lambda_{\text{paste}} = 0.8 \text{ W/(mK)}$	T _s = 25 °C	60	A
IF.	$\Lambda_{\text{paste}} = 0.8 \text{ W/(mK)}$ $T_i = 175 ^{\circ}\text{C}$	$T_s = 70 ^{\circ}\text{C}$	48	A
l _E	<u> </u>	$T_s = 70^{\circ} \text{C}$ $T_s = 25^{\circ} \text{C}$	68	A
l _F	λ_{paste} =2.5 W/(mK) T _i = 175 °C	$T_s = 25 \text{ C}$ $T_s = 70 \text{ °C}$	54	A
I	1., - 1.0 0	18-70 0	150	A
IFRM	t = 10 mg sin 1909	° T. = 150 °C		
I _{FSM}	$t_p = 10 \text{ ms, sin } 180^\circ$, 1 _j = 150 °C	270	A
Tj			-40 175	°C





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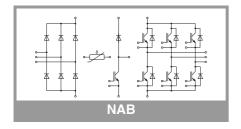
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Absolute Maximum Ratings						
Symbol	Conditions		Values	Unit		
Rectifier -	Diode					
V_{RRM}	T _j = 25 °C		1600	V		
I _F	λ _{paste} =0.8 W/(mK)	T _s = 25 °C	81	Α		
	T _j = 150 °C	T _s = 70 °C	60	Α		
I _F	λ_{paste} =2.5 W/(mK) T _j = 150 °C	T _s = 25 °C	92	Α		
		T _s = 70 °C	68	Α		
I _{FSM}	$t_p = 10 \text{ ms}$ sin 180°	T _j = 25 °C	700	Α		
		T _j = 150 °C	490	Α		
i ² t	$t_p = 10 \text{ ms}$	T _j = 25 °C	2500	A ² s		
sin 18	sin 180°	T _j = 150 °C	1200	A ² s		
T _j			-40 150	°C		
Module						
I _{t(RMS)}	T _{terminal} = 80 °C, 20 A per spring		80	Α		
T _{stg}	module without TIM		-40 125	°C		
V _{isol}	AC sinus 50 Hz, 1 min		2500	V		

Characteristics								
Symbol	Conditions		min.	typ.	max.	Unit		
Inverter -	Inverter - IGBT							
V _{CE(sat)}	$I_{\rm C} = 50 {\rm A}$	T _j = 25 °C		1.85	2.10	V		
	V _{GE} = 15 V chiplevel	T _j = 150 °C		2.20	2.40	V		
V_{CE0}	chiplevel	T _j = 25 °C		0.80	0.90	V		
	Chipievei	T _j = 150 °C		0.70	0.80	V		
r _{CE}	$V_{GE} = 15 \text{ V}$	T _j = 25 °C		21	24	mΩ		
	chiplevel	T _j = 150 °C		30	32	mΩ		
$V_{\text{GE(th)}}$	$V_{GE} = V_{CE}$, $I_C = 2 \text{ mA}$		5	5.8	6.5	V		
I _{CES}	$V_{GE} = 0 \text{ V}, V_{CE} = 12$	00 V, T _j = 25 °C			1	mA		
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		2.77		nF		
C _{oes}		f = 1 MHz		0.21		nF		
C _{res}		f = 1 MHz		0.16		nF		
Q_{G}	V _{GE} = - 8 V+ 15 V			280		nC		
R _{Gint}	T _j = 25 °C			4.0		Ω		
t _{d(on)}	$V_{CC} = 600 \text{ V}$	T _j = 150 °C		60		ns		
t _r	$I_{\rm C} = 50 {\rm A}$	T _j = 150 °C		35		ns		
E _{on}	$R_{G \text{ on}} = 15 \Omega$ $R_{G \text{ off}} = 15 \Omega$ $di/dt_{on} = 1700 \text{ A/}\mu\text{s}$	T _j = 150 °C		6		mJ		
t _{d(off)}		T _j = 150 °C		370		ns		
t _f	di/dt _{off} = 650 A/μs	T _j = 150 °C		60		ns		
E _{off}	V _{GE} = +15/-15 V	T _j = 150 °C		4.7		mJ		
R _{th(j-s)}	per IGBT, λ _{paste} =0.8	3 W/(mK)		0.71		K/W		
$R_{th(j-s)}$	per IGBT, λ _{paste} =2.5 W/(mK)			0.57		K/W		





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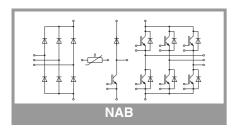
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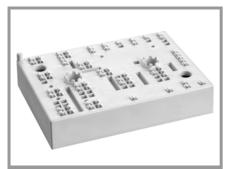
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Characte	eristics					
Symbol	Conditions		min.	typ.	max.	Unit
Chopper				71		
V _{CE(sat)}	I _C = 50 A	T _i = 25 °C		1.85	2.10	V
OL(Sat)	V _{GE} = 15 V	T _i = 150 °C		2.20	2.40	V
\/	chiplevel	-				
V _{CE0}	chiplevel	$T_j = 25 ^{\circ}\text{C}$ $T_i = 150 ^{\circ}\text{C}$		0.80	0.90	V
r	V 45.V	T _i = 150 °C		0.70	0.80	mΩ
r _{CE}	V _{GE} = 15 V chiplevel	T _i = 150 °C		30	32	mΩ
V _{GE(th)}	$V_{GE} = V_{CE}$, $I_C = 2 \text{ m}$	l '	5	5.8	6.5	V
I _{CES}	$V_{GE} = 0 \text{ V}, V_{CE} = 12$			3.0	1	mA
C _{ies}	VGE	f = 1 MHz		2.77		nF
Coes	$V_{CE} = 25 \text{ V}$	f = 1 MHz		0.21		nF
C _{res}	$V_{GE} = 0 V$	f = 1 MHz		0.16		nF
Q _G	V _{GE} = - 8 V+ 15 V			280		nC
R _{Gint}	T _i = 25 °C			4.0		Ω
t _{d(on)}	V _{CC} = 600 V	T _i = 150 °C		60		ns
t _r	$I_{\rm C} = 50 \text{ A}$	T _i = 150 °C		35		ns
E _{on}	$R_{G \text{ on}} = 15 \Omega$ $R_{G \text{ off}} = 15 \Omega$	T _i = 150 °C		6		mJ
t _{d(off)}	☐ NG off — 13 22	T _j = 150 °C		370		ns
t _f		T _j = 150 °C		60		ns
E _{off}	V _{GE} = +15/-15 V	T _j = 150 °C		4.7		mJ
R _{th(j-s)}	per IGBT, λ _{paste} =0.8	I 3 W/(mK)		0.71		K/W
R _{th(j-s)}	per IGBT, λ _{paste} =2.5 W/(mK)			0.57		K/W
Inverse -	· · · · · · · · · · · · · · · · · · ·	,	II			<u> </u>
$V_F = V_{EC}$	I _F = 50 A	T _i = 25 °C		2.22	2.54	V
	V _{GE} = 0 V	T _i = 150 °C		2.18	2.50	V
	chiplevel	T _i = 25 °C				
V _{F0}	chiplevel	,		1.30	1.50	V
		$T_j = 150 ^{\circ}\text{C}$ $T_i = 25 ^{\circ}\text{C}$		0.90	21	1
r _F	chiplevel	T _i = 150 °C		26	28	mΩ mΩ
	I _F = 50 A	T _i = 150 °C		45	20	A
Q _{rr}	di/dt _{off} = 1400 A/μs	T: = 150 °C		8.6		μC
	VGE = -15 V	T _i = 150 °C				-
Err	V _{CC} = 600 V	l ·		3.4		mJ
R _{th(j-s)}	per Diode, $\lambda_{paste}=0$. per Diode, $\lambda_{paste}=2$.			0.95		K/W
R _{th(j-s)}		5 W/(IIIK)		0.79		K/W
	eling - Diode	T 05 00	1	0.00	0.54	
$V_F = V_{EC}$	$V_{GE} = 0 V$	T _j = 25 °C		2.22	2.54	V
	chiplevel	T _j = 150 °C		2.18	2.50	V
17		T _j = 25 °C		1.30	1.50	V
V _{F0}	⊣ chiplevel			0.90	1.10	V
V _{F0}	chiplevel	T _j = 150 °C		0.30		
r _F		T _j = 25 °C		18	21	mΩ
	chiplevel	T _j = 25 °C T _j = 150 °C		18 26		mΩ mΩ
	chiplevel	$T_j = 25 \text{ °C}$ $T_j = 150 \text{ °C}$ $T_j = 150 \text{ °C}$		18 26 45	21	
r _F	chiplevel $I_F = 50 \text{ A}$ $di/dt_{off} = 1400 \text{ A/}\mu\text{s}$	$T_j = 25 \text{ °C}$ $T_j = 150 \text{ °C}$ $T_j = 150 \text{ °C}$ $T_j = 150 \text{ °C}$		18 26	21	mΩ
r _F	chiplevel	$T_j = 25 \text{ °C}$ $T_j = 150 \text{ °C}$ $T_j = 150 \text{ °C}$		18 26 45	21	mΩ A
r _F	chiplevel $I_F = 50 \text{ A}$ $di/dt_{off} = 1400 \text{ A/}\mu\text{s}$ $V_{GE} = -15 \text{ V}$	$T_{j} = 25 ^{\circ}\text{C}$ $T_{j} = 150 ^{\circ}\text{C}$ $T_{j} = 150 ^{\circ}\text{C}$ $T_{j} = 150 ^{\circ}\text{C}$ $T_{j} = 150 ^{\circ}\text{C}$		18 26 45 8.6	21	mΩ A μC



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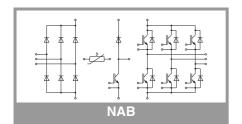
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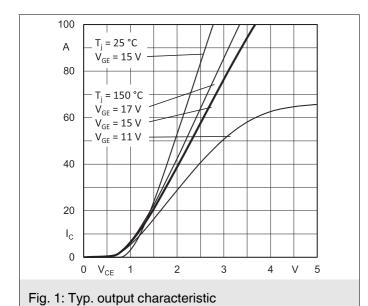
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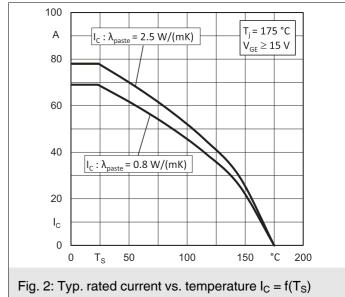
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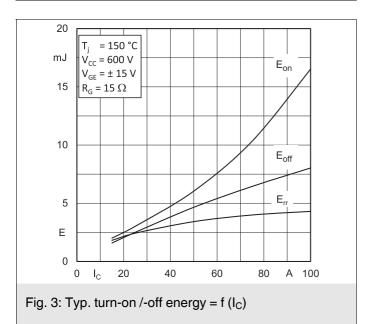
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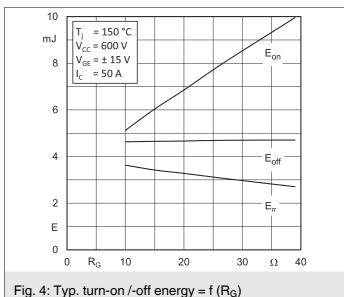
Characteristics							
Symbol	Conditions		min.	typ.	max.	Unit	
Rectifier -	Diode						
$V_F = V_{EC}$	I _F = 25 A	T _j = 25 °C		1.00	1.21	V	
	chiplevel	T _j = 125 °C		0.90	1.10	V	
V_{F0}	chiplevel	T _j = 25 °C		0.88	0.98	V	
	Criipievei	T _j = 125 °C		0.73	0.83	V	
r _F	chiplevel	T _j = 25 °C		4.8	9.2	mΩ	
		T _j = 125 °C		6.8	11	mΩ	
I _R	T _j = 145 °C, V _{RRM}				1.1	mA	
R _{th(j-s)}	per Diode, λ _{paste} =0.8 W/(mK)			0.9		K/W	
R _{th(j-s)}	per Diode, λ _{paste} =2.5 W/(mK)			0.75		K/W	
Module							
Ms	to heat sink		2		2.5	Nm	
w				82		g	
L _{CE}				-		nH	
Temperat	ure Sensor						
R ₁₀₀	T _r =100°C (R ₂₅ =1000Ω)			1670 ± 3%		Ω	
R _(T)	$\begin{aligned} &R_{(T)} = 1000\Omega[1 + A(T-25^{\circ}C) + B(T-25^{\circ}C)^{2}]\\ &, A = 7.635^{*}10^{-3^{\circ}}C^{-1},\\ &B = 1.731^{*}10^{-5^{\circ}}C^{-2} \end{aligned}$						

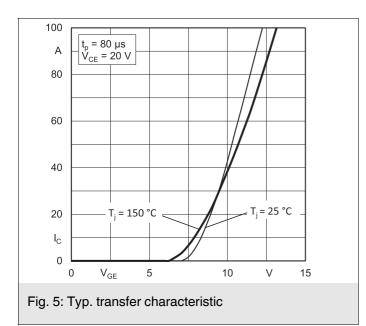


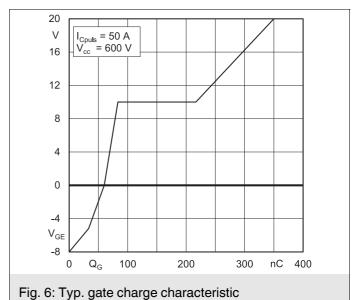


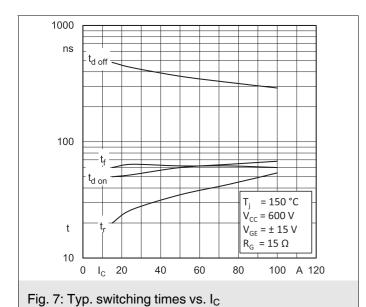


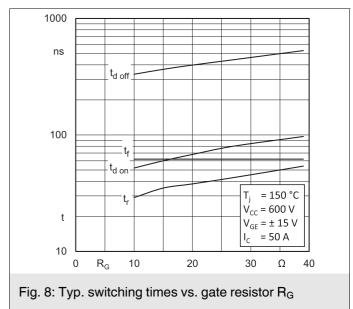


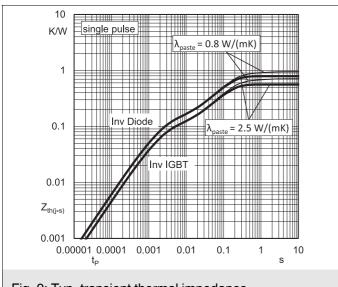




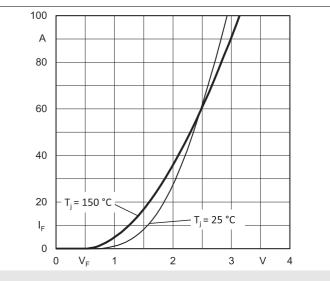


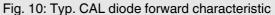












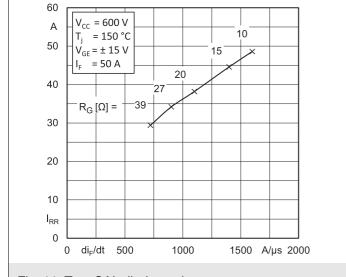


Fig. 11: Typ. CAL diode peak reverse recovery current

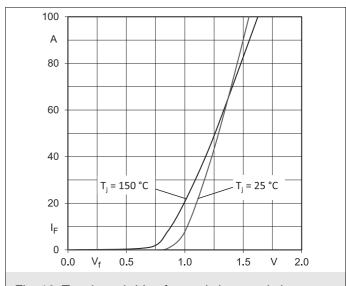
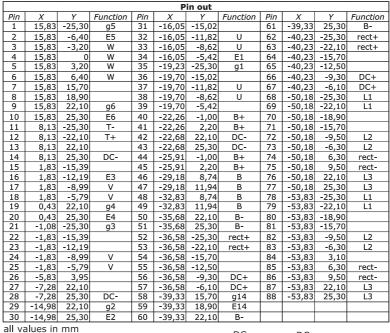
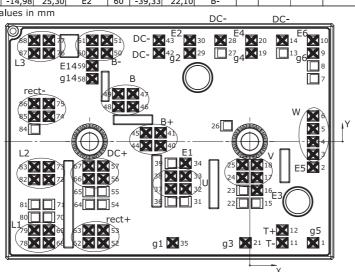
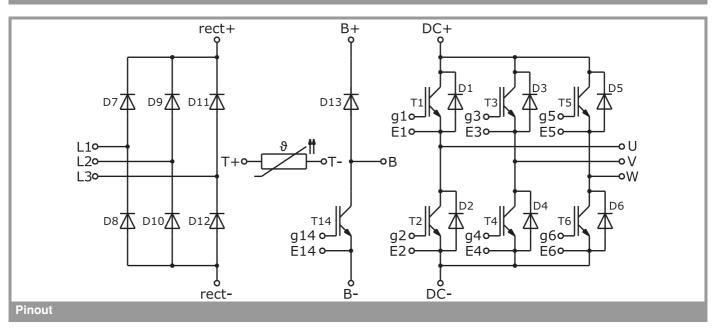


Fig. 12: Typ. input bridge forward characteristic





Pinout and Dimensions



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

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